

# Arian Rahimi

## List of Publications by Year in descending order

Source: <https://exaly.com/author-pdf/10243272/publications.pdf>

Version: 2024-02-01

12  
papers

103  
citations

1937685

4  
h-index

2272923

4  
g-index

12  
all docs

12  
docs citations

12  
times ranked

71  
citing authors

#	ARTICLE	IF	CITATIONS
1	Study on Cu/Ni Nano Superlattice Conductors for Reduced RF Loss. IEEE Microwave and Wireless Components Letters, 2016, 26, 258-260.	3.2	22
2	Cu/Co Multilayer-Based High Signal Integrity and Low RF Loss Conductors for 5G/Millimeter Wave Applications. IEEE Transactions on Microwave Theory and Techniques, 2018, 66, 3773-3780.	4.6	21
3	A surface micromachined broadband millimeter-wave filter using quarter-mode substrate integrated waveguide loaded with complementary split ring resonator. , 2014, , .		18
4	Cylindrical radial superlattice conductors for low loss microwave components. Journal of Applied Physics, 2015, 117, 103911.	2.5	11
5	Integrated low loss RF passive components on glass interposer technology. , 2015, , .		8
6	Flexible Liquid Crystal Polymer based complementary split ring resonator loaded quarter mode substrate integrated waveguide filters for compact and wearable broadband RF applications. , 2014, , .		6
7	High-Q K-band integrated inductors using Cu/Ni nano-superlattice conductors. , 2015, , .		6
8	Magnetically tunable nano-superlattice metaconductors for RF applications. , 2016, , .		5
9	Millimeter-wave bandpass filter on LCP using CSRR-loaded triangular-shape quarter-mode substrate integrated waveguide. Microwave and Optical Technology Letters, 2015, 57, 1782-1784.	1.4	4
10	High Q-factor Ku band inductor using Cylindrical Radial Superlattice conductor and air-lifted architecture. , 2014, , .		1
11	Hybrid cylindrical radial superlattice conductor-based air-lifted RF inductors with ultra-high quality factor for UWB and K-bands. , 2016, , .		1
12	High-Q On-Chip Capacitors Featuring "Self-Inductance Cancellation" for RF and mm-Wave Applications. IEEE Microwave and Wireless Components Letters, 2022, 32, 668-671.	3.2	0